Preferred Device

Dual Common Base-Collector Bias Resistor Transistors

NPN and PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

The BRT (Bias Resistor Transistor) contains a single transistor with a monolithic bias network consisting of two resistors; a series base resistor and a base-emitter resistor. These digital transistors are designed to replace a single device and its external resistor bias network. The BRT eliminates these individual components by integrating them into a single device. In the NSB1010XV5T5, two complementary BRT devices are housed in the SOT-553 package which is ideal for low power surface mount applications where board space is at a premium.

- Simplifies Circuit Design
- Reduces Board Space
- Reduces Component Count
- Available in 8 mm, 7 inch Tape and Reel
- This device is manufactured with a Pb-Free external lead finish only.

MAXIMUM RATINGS ($T_A = 25^{\circ}C$ unless otherwise noted, common for Q_1 and Q_2 , – minus sign for Q_1 (PNP) omitted)

| Rating | Symbol | Value | Unit |
|---------------------------|----------------|-------|------|
| Collector-Base Voltage | V_{CBO} | 50 | Vdc |
| Collector-Emitter Voltage | V_{CEO} | 50 | Vdc |
| Collector Current | I _C | 100 | mAdc |

THERMAL CHARACTERISTICS

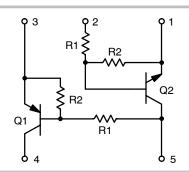
| Characteristic (One Junction Heated) | Symbol | Max | Unit |
|--|-----------------------------------|------------------------------|-------------|
| Total Device Dissipation T _A = 25°C Derate above 25°C | P _D | 357 (Note 1) 2.9 (Note 1) | mW mW/°C |
| Thermal Resistance Junction-to-Ambient | $R_{\theta JA}$ | 350 (Note 1) | °C/W |
| Characteristic (Both Junctions Heated) | Symbol | Max | Unit |
| Total Device Dissipation T _A = 25°C Derate above 25°C | P _D | 500 (Note 1) 4.0 (Note 1) | mW mW/°C |
| Thermal Resistance Junction-to-Ambient | $R_{\theta JA}$ | 250 (Note 1) | °C/W |
| Junction and Storage Temperature | T _J , T _{stg} | -55 to +150 | °C |

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. FR-4 @ Minimum Pad.



http://onsemi.com





MARKING DIAGRAM



US = Specific Device Code D = Date Code

ORDERING INFORMATION

| Device | Package | Shipping [†] | | |
|--------------|----------------------|--------------------------------|--|--|
| NSB1010XV5T5 | SOT-553 (Pb-Free) | 2 mm pitch 8000/Tape & Reel | | |

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

ELECTRICAL CHARACTERISTICS ($T_A = 25^{\circ}C$ unless otherwise noted)

| Characteristic | Symbol | Min | Тур | Max | Unit |
|---|--------------------------------|------|-----|-------|------|
| Q1 TRANSISTOR: PNP OFF CHARACTERISTICS | | | | | |
| Collector-Base Cutoff Current (V _{CB} = -50 V, I _E = 0) | I _{CBO} | - | _ | -100 | nAdc |
| Collector-Emitter Cutoff Current (V _{CB} = -50 V, I _B = 0) | I _{CEO} | - | _ | -500 | nAdc |
| Emitter-Base Cutoff Current ($V_{EB} = -6.0 \text{ V}, I_{C} = 0$) | I _{EBO} | - | _ | -1.5 | mAdc |
| Collector-Base Breakdown Voltage ($I_C = -10 \mu A, I_E = 0$) | V _{(BR)CBO} | -50 | _ | _ | Vdc |
| Collector-Emitter Breakdown Voltage (Note 2) (I _C = -2.0 mA, I _B = 0) | V _{(BR)CEO} | -50 | - | _ | Vdc |
| ON CHARACTERISTICS (Note 2) | | | | | |
| Collector-Emitter Saturation Voltage (I _C = −10 mA, I _B = −1.0 mA) | V _{CE(sat)} | _ | _ | -0.25 | Vdc |
| DC Current Gain (V _{CE} = -10 V, I _C = -5.0 mA) | h _{FE} | 15 | 27 | - | - |
| Output Voltage (on) (V_{CC} = -5.0 V, V_B = -2.5 V, R_L = 1.0 k Ω) | V _{OL} | - | - | -0.2 | Vdc |
| Output Voltage (off) (V_{CC} = -5.0 V, V_B = -0.5 V, R_L = 1.0 k Ω) | V _{OH} | -4.9 | - | - | Vdc |
| Input Resistor | R ₁ | 3.3 | 4.7 | 6.1 | kΩ |
| Resistor Ratio | R ₁ /R ₂ | 0.8 | 1.0 | 1.2 | _ |
| Q2 TRANSISTOR: NPN OFF CHARACTERISTICS | | | | | |
| Collector-Base Cutoff Current (V _{CB} = 50 V, I _E = 0) | I _{CBO} | _ | _ | 100 | nAdc |
| Collector-Emitter Cutoff Current (V _{CB} = 50 V, I _B = 0) | I _{CEO} | - | _ | 500 | nAdc |
| Emitter-Base Cutoff Current (V _{EB} = 6.0, I _C = 5.0 mA) | I _{EBO} | - | - | 0.5 | mAdc |
| ON CHARACTERISTICS | | | | | |
| Collector-Base Breakdown Voltage (I _C = 10 μA, I _E = 0) | V _{(BR)CBO} | 50 | - | - | Vdc |
| Collector-Emitter Breakdown Voltage (I _C = 2.0 mA, I _B = 0) | V _{(BR)CEO} | 50 | - | - | Vdc |
| DC Current Gain (V _{CE} = 10 V, I _C = 5.0 mA) | h _{FE} | 35 | 60 | - | |
| Collector-Emitter Saturation Voltage (I _C = 10 mA, I _B = 0.3 mA) | V _{CE(SAT)} | - | - | 0.25 | Vdc |
| Output Voltage (on) (V_{CC} = 5.0 V, V_B = 2.5 V, R_L = 1.0 k Ω) | V _{OL} | - | _ | 0.2 | Vdc |
| Output Voltage (off) (V_{CC} = 5.0 V, V_B = 0.5 V, R_L = 1.0 k Ω) | V _{OH} | 4.9 | - | - | Vdc |
| Input Resistor | R1 | 7.0 | 10 | 13 | kΩ |
| Resistor Ratio | R1/R2 | 0.8 | 1.0 | 1.2 | - |

^{2.} Pulse Test: Pulse Width < 300 μs, Duty Cycle < 2.0%.

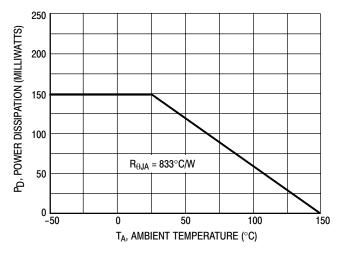


Figure 1. Derating Curve

TYPICAL ELECTRICAL CHARACTERISTICS — PNP TRANSISTOR

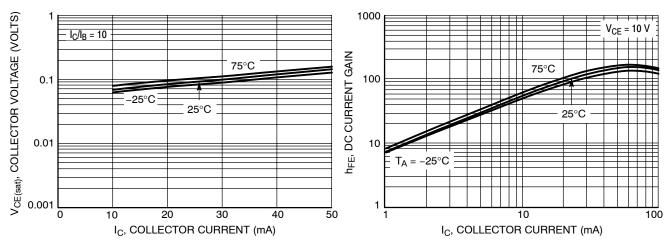


Figure 2. $V_{CE(sat)}$ versus I_C

Figure 3. DC Current Gain

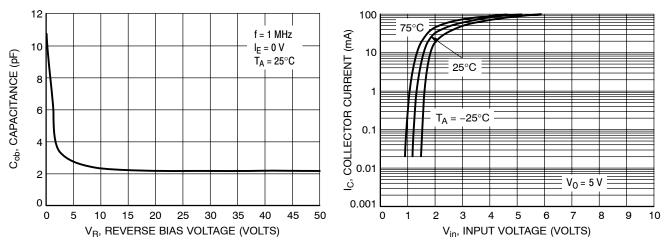


Figure 4. Output Capacitance

Figure 5. Output Current versus Input Voltage

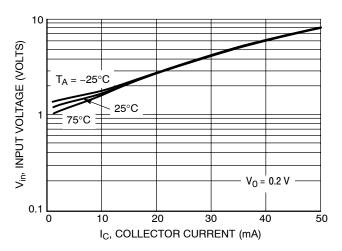


Figure 6. Input Voltage versus Output Current

TYPICAL ELECTRICAL CHARACTERISTICS — NPN TRANSISTOR

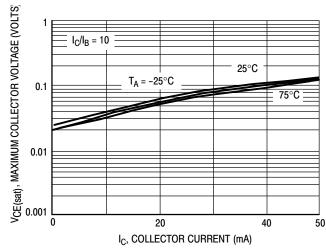


Figure 7. V_{CE(sat)} versus I_C

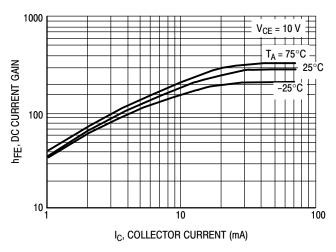


Figure 8. DC Current Gain

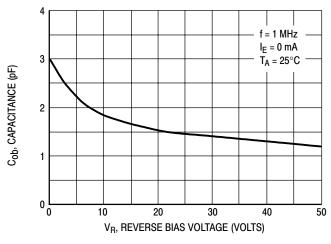


Figure 9. Output Capacitance

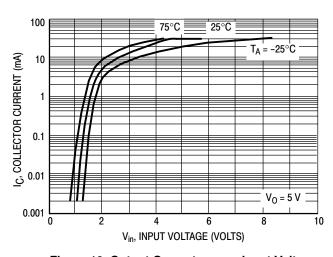


Figure 10. Output Current versus Input Voltage

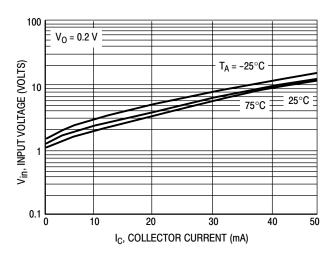
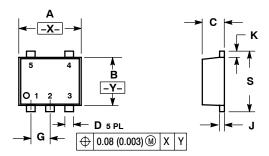


Figure 11. Input Voltage versus Output Current

PACKAGE DIMENSIONS

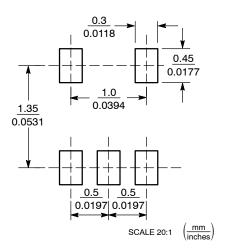
SOT-553 **5-LEAD PACKAGE** CASE 463B-01 **ISSUE A**



- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

| | MILLIMETERS | | INCHES | | |
|-----|-------------|------|-----------|-------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 1.50 | 1.70 | 0.059 | 0.067 | |
| В | 1.10 | 1.30 | 0.043 | 0.051 | |
| С | 0.50 | 0.60 | 0.020 | 0.024 | |
| D | 0.17 | 0.27 | 0.007 | 0.011 | |
| G | 0.50 BSC | | 0.020 BSC | | |
| J | 0.08 | 0.18 | 0.003 | 0.007 | |
| K | 0.10 | 0.30 | 0.004 | 0.012 | |
| S | 1.50 | 1.70 | 0.059 | 0.067 | |

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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